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- 8-Bit Resolution
- 2.7-V to 3.6-V V<sub>CC</sub>
- **Easy Microprocessor Interface or Stand-Alone Operation**
- Operates Ratiometrically or With V<sub>CC</sub> Reference
- 4- or 8-Channel Multiplexer Options With **Address Logic**
- Input Range 0 V to V<sub>CC</sub> With V<sub>CC</sub> Reference

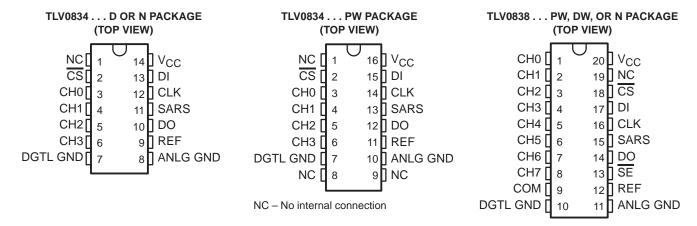
- **Remote Operation With Serial Data Link**
- Inputs and Outputs Are Compatible With TTL and MOS
- Conversion Time of 32 µs at  $f_{(CLK)} = 250 \text{ kHz}$
- **Functionally Equivalent to the ADC0834** and ADC0838 at 3-V Supply Without the **Internal Zener Regulator Network**
- Total Unadjusted Error . . . ±1 LSB

## description

These devices are 8-bit successive-approximation analog-to-digital converters, each with an input-configurable multichannel multiplexer and serial input/output. The serial input/output is configured to interface with standard shift registers or microprocessors. Detailed information on interfacing with most popular microprocessors is readily available from the factory.

The TLV0834 (4-channel) and TLV0838 (8-channel) multiplexer is software-configured for single-ended or differential inputs as well as pseudodifferential input assignments. The differential analog voltage input allows for common-mode rejection or offset of the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding of any smaller analog voltage span to the full 8 bits of resolution.

The TLV0834C and TLV0838C are characterized for operation from 0°C to 70°C. The TLV0834I and TLV0838I are characterized for operation from -40°C to 85°C.



#### **AVAILABLE OPTIONS**

	PACKAGE							
TA	SMALL OUTLINE (D)	SMALL OUTLINE (DW)	1	TIC DIP N)	TSSOP (PW)			
0°C to 70°C	TLV0834CD	TLV0838CDW	TLV0834CN	TLV0838CN	TLV0834CPW	TLV0838CPW		
-40°C to 85°C	TLV0834ID	TLV0838IDW	TLV0834IN	TLV0838IN	TLV0834IPW	TLV0838IPW		

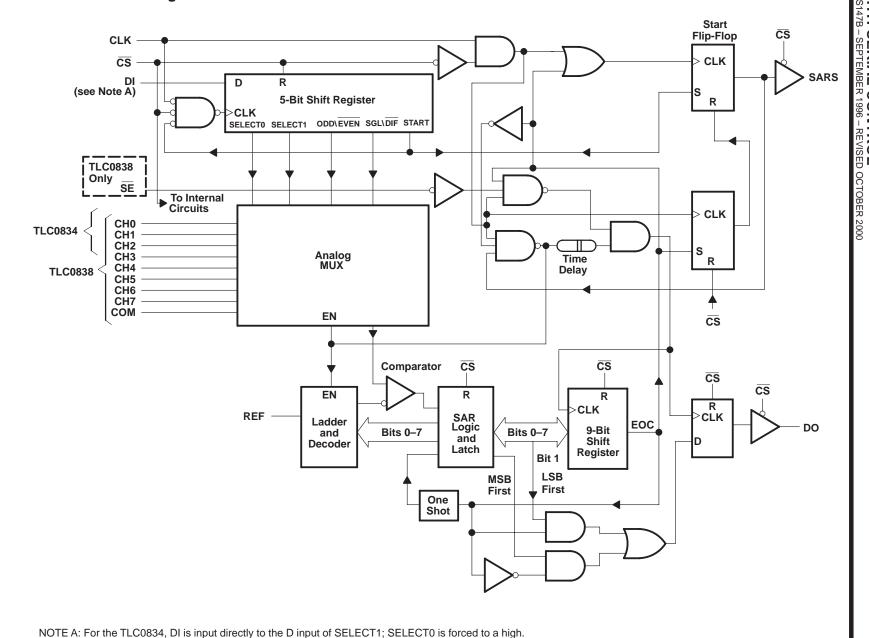


testing of all parameters

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## functional block diagram



TLV0834I, TLV0838C,

V0838C, TLV0838I 「O-DIGITAL CONVERTERS

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## functional description

The TLV0834 and TLV0838 use a sample-data-comparator structure that converts differential analog inputs by a successive-approximation routine. Operation of both devices is similar with the exception of  $\overline{SE}$ , an analog common input, and multiplexer addressing. The input voltage to be converted is applied to a channel terminal and is compared to ground (single ended), to an adjacent input (differential), or to a common terminal (pseudo differential) that can be an arbitrary voltage. The input terminals are assigned a positive (+) or negative (–) polarity. When the signal input applied to the assigned positive terminal is less than the signal on the negative terminal, the converter output is all zeros.

Channel selection and input configuration are under software control using a serial-data link from the controlling processor. A serial-communication format allows more functions to be included in a converter package with no increase in size. In addition, it eliminates the transmission of low-level analog signals by locating the converter at the analog sensor and communicating serially with the controlling processor. This process returns noise-free digital data to the processor.

A particular input configuration is assigned during the multiplexer-addressing sequence. The multiplexer address shifts into the converter through the data input (DI) line. The multiplexer address selects the analog inputs to be enabled and determines whether the input is single ended or differential. When the input is differential, the polarity of the channel input is assigned. Differential inputs are assigned to adjacent channel pairs. For example, channel 0 and channel 1 may be selected as a differential pair. These channels cannot act differentially with any other channel. In addition to selecting the differential mode, the polarity may also be selected. Either channel of the channel pair may be designated as the negative or positive input.

The common input on the TLV0838 can be used for a pseudodifferential input. In this mode, the voltage on the common input is considered to be the negative differential input for all channel inputs. This voltage can be any reference potential common to all channel inputs. Each channel input can then be selected as the positive differential input. This feature is useful when all analog circuits are biased to a potential other than ground.

A conversion is initiated by setting  $\overline{CS}$  low, which enables all logic circuits.  $\overline{CS}$  must be held low for the complete conversion process. A clock input is then received from the processor. On each low-to-high transition of the clock input, the data on DI is clocked into the multiplexer-address shift register. The first logic high on the input is the start bit. A 3- to 4-bit assignment word follows the start bit. On each successive low-to-high transition of the clock input, the start bit and assignment word are shifted through the shift register. When the start bit is shifted into the start location of the multiplexer register, the input channel is selected and conversion starts. The SAR status output (SARS) goes high to indicate that a conversion is in progress, and DI to the multiplexer shift register is disabled for the duration of the conversion.

An interval of one clock period is automatically inserted to allow the selected multiplexed channel to settle. DO comes out of the high-impedance state and provides a leading low for one clock period of multiplexer settling time. The SAR comparator compares successive outputs from the resistive ladder with the incoming analog signal. The comparator output indicates whether the analog input is greater than or less than the resistive-ladder output. As the conversion proceeds, conversion data is simultaneously output from DO, with the most significant bit (MSB) first. After eight clock periods, the conversion is complete and SARS goes low.

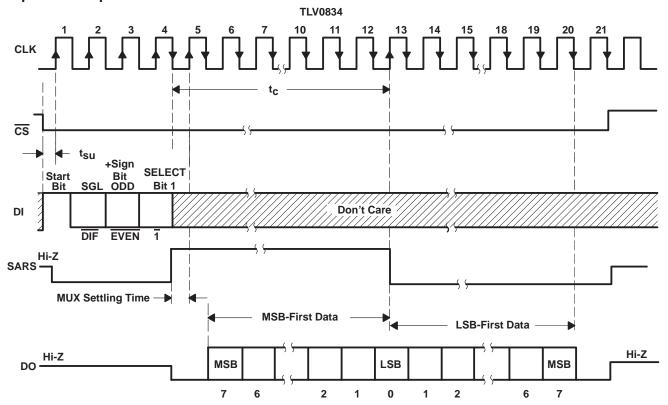
The TLV0834 outputs the least-significant-bit (LSB) first data after the MSB-first data stream. When  $\overline{SE}$  is held high on the TLV0838, the value of the LSB remains on the data line. When  $\overline{SE}$  is forced low, the data is then clocked out as LSB-first data. (To output LSB first,  $\overline{SE}$  must first go low, then the data stored in the 9-bit shift register outputs LSB first.) When  $\overline{CS}$  goes high, all internal registers are cleared. At this time, the output circuits go to the high-impedance state. If another conversion is desired,  $\overline{CS}$  must make a high-to-low transition followed by address information.

DI and DO can be tied together and controlled by a bidirectional processor I/O bit received on a single wire. This is possible because DI is only examined during the multiplexer-addressing interval and DO is still in the high-impedance state.



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## sequence of operation



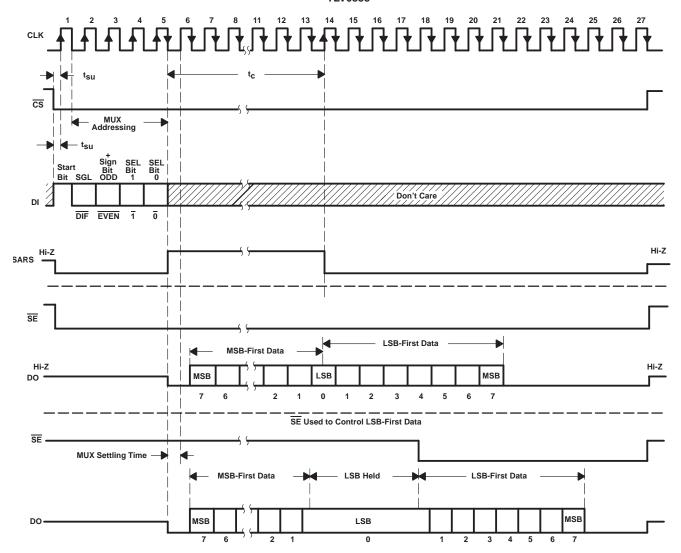
TLV0834 MUX-ADDRESS CONTROL LOGIC TABLE

	MUX ADDRES	CHANNEL NUMBER					
SGL/DIF	ODD/EVEN	SELECT BIT 1	CH0	CH1	CH2	СНЗ	
L	L	L	+	_			
L	L	Н			+	_	
L	Н	L	_	+			
L	Н	Н			_	+	
Н	L	L	+				
Н	L	Н			+		
Н	Н	L		+			
Н	Н	Н				+	

H = high level, L = low level, - or + = terminal polarity for the selected input channel

## sequence of operation (continued)

#### TLV0838





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#### TLV0838 MUX-ADDRESS CONTROL LOGIC TABLE

	MUX ADDRESS				SE	LECTE	D CHA	NNEL	NUMB	ER		
SGL/DIF	ODD/EVEN	SEL	ECT		0		1		2		3	СОМ
3GL/DIF	ODD/EVEN	1	0	CH0	CH1	CH2	CH3	CH4	CH5	CH6	CH7	
L	L	L	L	+	-							
L	L	L	Н			+	_					
L	L	Н	L					+	_			
L	L	Н	Н							+	_	
L	Н	L	L	-	+							
L	Н	L	Н			_	+					
L	Н	Н	L					-	+			
L	Н	Н	Н							-	+	
Н	L	L	L	+								-
Н	L	L	Н			+						-
н	L	Н	L					+				-
н	L	Н	Н							+		-
Н	Н	L	L		+							_
н	Н	L	Н				+					-
н	Н	Н	L						+			-
Н	Н	Н	Н			_			_	-	+	_

H = high level, L = low level, - or + = polarity of external input

## absolute maximum ratings over recommended operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1)		6.5 V
Input voltage range: Logic		$\dots$ -0.3 V to V <sub>CC</sub> + 0.3 V
Analog		$\dots$ -0.3 V to V <sub>CC</sub> + 0.3 V
Input current, I <sub>I</sub>		±5 mA
Total input current		±20 mA
Operating free-air temperature range, T <sub>A</sub> :	C suffix	0°C to 70°C
	I suffix	40°C to 85°C
Storage temperature range, T <sub>stq</sub>		65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from	case for 10 seconds: N package	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to the network ground terminal.



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## recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub> (see clock frequency open	erating conditions)		2.7	3.3	3.6	V
igh-level input voltage, V <sub>IH</sub>						V
Low-level input voltage, V <sub>IL</sub>					0.8	V
Clock frequency, f(CLK)	V <sub>CC</sub> = 2.7 V		10		250	kHz
Clock frequency, f(CLK)	V <sub>CC</sub> = 3.3 V		10		600	kHz
Clock duty cycle (see Note 2)			40%		60%	
Pulse duration, CS high, t <sub>W</sub>			220			ns
Setup time, CS low, SE low, or data valid befo	re CLK↑, t <sub>su</sub>		350			ns
Hold time, data valid after CLK↑, th						ns
Operating free air temperature Te	C suffix		0		70	°C
Operating free-air temperature, T <sub>A</sub>	I suffix		-40		85	30

NOTE 2: The clock-duty-cycle range ensures proper operation at all clock frequencies. When a clock frequency is used outside the recommended duty-cycle range, the minimum pulse duration (high or low) is 1 µs.

# electrical characteristics over recommended range of operating free-air temperature, $V_{CC} = 3.3 \text{ V}$ , $f_{(CLK)} = 250 \text{ kHz}$ (unless otherwise noted)

## digital section

	PARAMETER	TEOT 0	ONDITIONS <sup>†</sup>	(	SUFFIX		ı	SUFFIX		UNIT
	PARAMETER	TEST C	ONDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
\/a	VOH High-level output voltage		$I_{OH} = -360  \mu A$	2.8			2.4			V
VOH			$I_{OH} = -10 \mu A$	2.9			2.8			V
VOL	Low-level output voltage	$V_{CC} = 3 V$	$I_{OL} = 1.6 \text{ mA}$			0.34			0.4	V
lн	High-level input current	V <sub>IH</sub> = 3.6 V			0.005	1		0.005	1	μΑ
I <sub>IL</sub>	Low-level input current	V <sub>IL</sub> = 0			-0.005	-1		-0.005	-1	μΑ
IOH	High-level output (source) current	At V <sub>OH</sub> , DO	$= 0 \text{ V}, T_A = 25^{\circ}\text{C}$	-6.5	-15		-6.5	-15		mA
loL	Low-level output (sink) current	At V <sub>OL</sub> , DO	= V <sub>CC</sub> , T <sub>A</sub> = 25°C	8	16		8	16		mA
	High-impedance-state output	$V_0 = 3.3 V$	T <sub>A</sub> = 25°C		0.01	3		0.01	3	
loz	current (DO or SARS)	$V_{O} = 0$ ,	T <sub>A</sub> = 25°C		-0.01	-3		-0.01	-3	μΑ
Ci	Input capacitance							5		рF
Co	Output capacitance							5		pF

<sup>†</sup> All parameters are measured under open-loop conditions with zero common-mode input voltage (unless otherwise specified).



<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

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# electrical characteristics over recommended range of operating free-air temperature, $V_{CC}$ = 3.3 V, $f_{(CLK)}$ = 250 kHz (unless otherwise noted) (continued)

#### analog and converter section

	PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
VIC	Common-mode input voltage		See Note 3	-0.05 to V <sub>CC</sub> +0.05			>
	On channel	V <sub>I</sub> = 3.3 V			1		
lar and	Ctondby input gurrent (ass Note 4)	Off channel	V <sub>I</sub> = 0			-1	
II(stdby)	I <sub>I</sub> (stdby) Standby input current (see Note 4)	On channel	V <sub>I</sub> = 0			-1	μΑ
		Off channel	V <sub>I</sub> = 3.3 V			1	
ri(REF)	Input resistance to REF			1.3	2.4	5.9	kΩ

#### total device

PARAMETER	MIN	TYP <sup>‡</sup>	MAX	UNIT
ICC Supply current		0.2	0.75	mA

<sup>†</sup> All parameters are measured under open-loop conditions with zero common-mode input voltage.

NOTES: 3. When channel IN- is more positive than channel IN+, the digital output code is 0000 0000. Connected to each analog input are two on-chip diodes that conduct forward current for analog input voltages one diode drop above V<sub>CC</sub>. Care must be taken during testing at low V<sub>CC</sub> levels (3 V) because high-level analog input voltage (3.6 V) can, especially at high temperatures, cause the input diode to conduct and cause errors for analog inputs that are near full scale. As long as the analog voltage does not exceed the supply voltage by more than 50 mV, the output code is correct. To achieve an absolute 0- to 3.3-V input range requires a minimum V<sub>CC</sub> of 3.25 V for all variations of temperature and load.

4. Standby input currents go in or out of the on or off channels when the A/D converter is not performing conversion and the clock is in a high or low steady-state condition.

# operating characteristics, $V_{CC}$ = 3.3 V, $f_{(CLK)}$ = 250 kHz, $t_r$ = $t_f$ = 20 ns, $T_A$ = 25°C (unless otherwise noted)

	PARAMETER		TEST CONDITIONS§	MIN	TYP	MAX	UNIT
	Supply-voltage variation error		V <sub>CC</sub> = 3 V to 3.6 V		±1/16	±1/4	LSB
	Total unadjusted error (see Note 5)	$V_{ref} = 3.3 \text{ V},  T_A = MIN \text{ to MAX}$			±1	LSB	
	Common-mode error	Differential mode		±1/16	±1/4	LSB	
	Propagation delay time, output data after	MSB-first data	$C_1 = 100pF$			500	ns
<sup>t</sup> pd	CLK↓ (see Note 6)	LSB-first data	- С_ = 100рг			200	115
			$C_L = 10 \text{ pF},  R_L = 10 \text{ k}\Omega$			80	no
tdis Output disable time, DO or SARS after CS↑			$C_L = 100  pF$ , $R_L = 2  k\Omega$			250	ns
t <sub>C</sub>	Conversion time (multiplexer-addressing time				8	clock periods	

<sup>§</sup> All parameters are measured under open-loop conditions with zero common-mode input voltage. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Total unadjusted error includes offset, full-scale, linearity, and multiplexer errors.

6. The MSB-first data is output directly from the comparator and, therefore, requires additional delay to allow for comparator response time.



<sup>‡</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

### PARAMETER MEASUREMENT INFORMATION

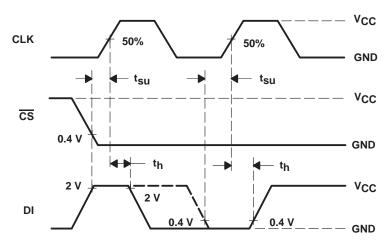


Figure 1. Data-Input Timing

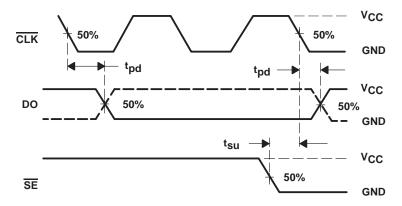
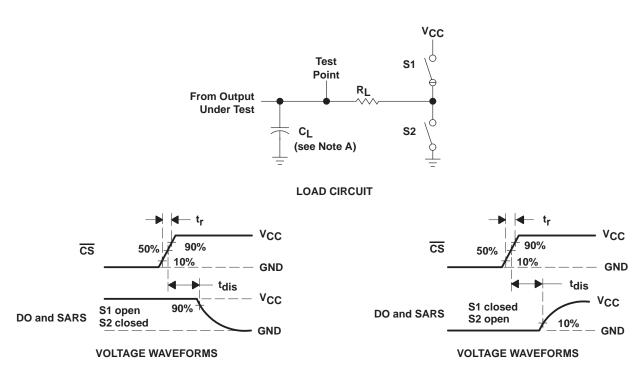


Figure 2. Data-Output Timing

#### PARAMETER MEASUREMENT INFORMATION

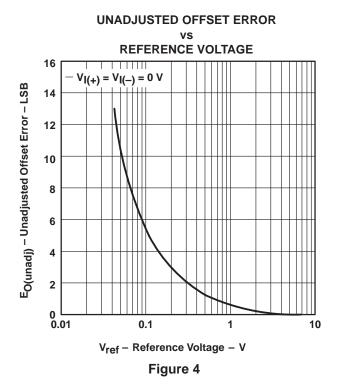


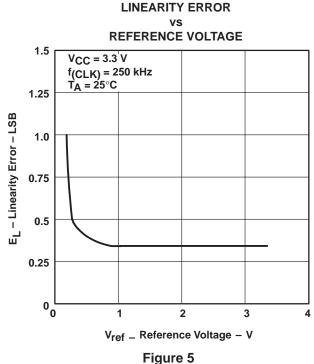
NOTE A:  $C_L$  includes probe and jig capacitance.

Figure 3. Output Disable Time Test Circuit and Voltage Waveforms

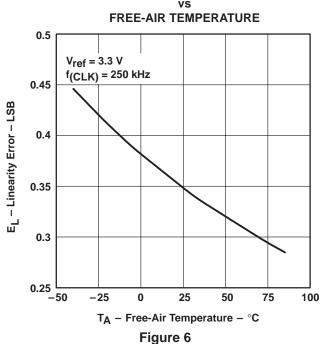


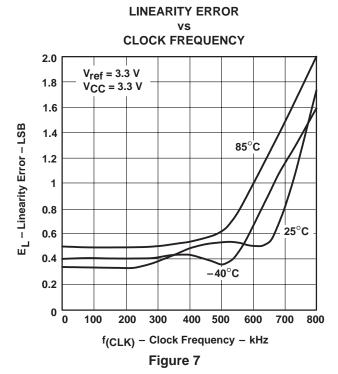
#### TYPICAL CHARACTERISTICS



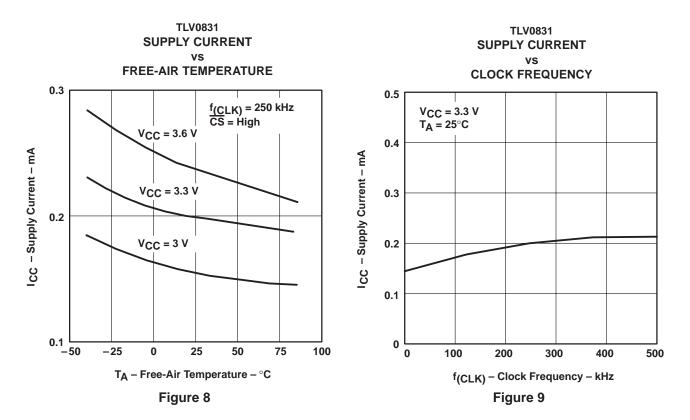


## **LINEARITY ERROR** vs FREE-AIR TEMPERATURE





### TYPICAL CHARACTERISTICS



## **OUTPUT CURRENT** FREE-AIR TEMPERATURE 16.5 V<sub>CC</sub> = 3.3 V 16 IOL(DO = 3.3 V)IO - Output Current - mA 15.5 -IOH(DO = 0 V)15 -IOH (DO = 2.4 V)14.5 IOL(DO = 0.4 V)14 — -50 -25 25 50 75 100 T<sub>A</sub> - Free-Air Temperature - °C



Figure 10

## **TYPICAL CHARACTERISTICS**

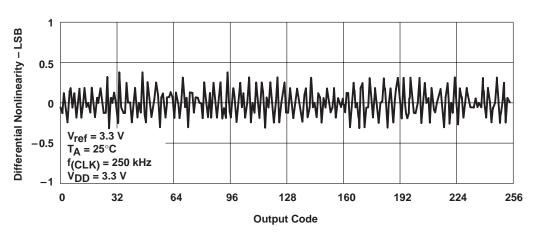


Figure 11. Differential Nonlinearity With Output Code

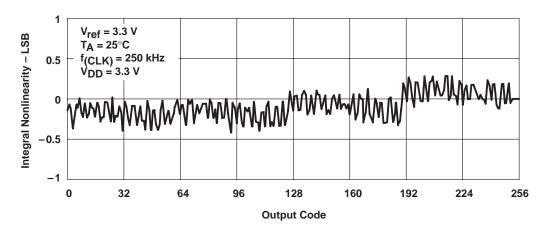


Figure 12. Integral Nonlinearity With Output Code

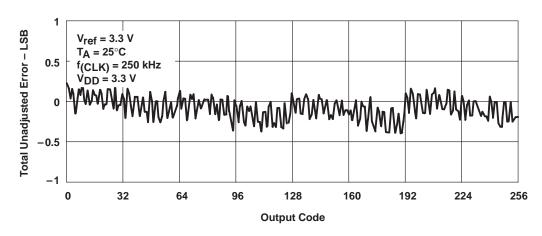


Figure 13. Total Unadjusted Error With Output Code



## **PACKAGE OPTION ADDENDUM**





## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLV0834CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834CPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0834INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0834IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0834IPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0838CNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0838CPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





om 17-Jun-2008

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLV0838CPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838CPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0838INE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLV0838IPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV0838IPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## PACKAGE OPTION ADDENDUM



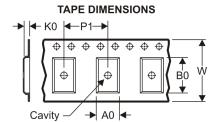
17-Jun-2008

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

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## TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
Г	W	Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nomina	ll .											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV0834CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV0834CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV0834IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV0834IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV0838CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TLV0838IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1



## PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV0834CDR	SOIC	D	14	2500	346.0	346.0	33.0
TLV0834CPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
TLV0834IDR	SOIC	D	14	2500	346.0	346.0	33.0
TLV0834IPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
TLV0838CPWR	TSSOP	PW	20	2000	346.0	346.0	33.0
TLV0838IPWR	TSSOP	PW	20	2000	346.0	346.0	33.0

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